

ABSTRACT

METHOD FOR FORMING LAMINATE AND LAMINATING DEVICE

A surface of a laminate base body including a projection is caused to penetrate at least a film-shaped laminating body and surely laminated by a simple configuration, and a laminate thereof is formed at a uniform thickness without an occurrence of voids. A laminating device is provided with a heating unit configured to heat at least an insulating resin film; an upper plate and a lower plate configured to be capable of opening and closing, and configured to form a chamber that becomes sealed upon closing; a receiving member having an elasticity and disposed on the upper plate so as to oppose the insulating resin film layered on one side of a semiconductor wafer on which bumps are formed; an elastic membrane body disposed on the lower plate so as to oppose the semiconductor wafer on which the insulating resin film is layered; a vacuuming unit configured to vacuum inside of the chamber; and a compressing unit configured to bloat the elastic membrane body so as to compress the semiconductor wafer and the insulating resin film between the elastic membrane body and the receiving member.

FIG. 1